November 2013



FQPF12N60C N-Channel QFET[®] MOSFET

600 V, 12 A, $650~m\Omega$

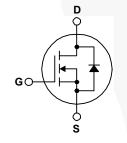
Description

These N-Channel enhancement mode power field effect transistors are produced using Fairchild's proprietary, planar stripe, DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficient switched mode power supplies, active power factor correction, electronic lamp ballast based on half bridge topology.

Features

- 12 A, 600 V, $R_{DS(on)}$ = 650 m Ω (Max.) @ V_{GS} = 10 V, I_{D} = 6 A
- Low Gate Charge (Typ. 48 nC)
- Low Crss (Typ. 21 pF)
- 100% Avalanche Tested





Absolute Maximum Ratings $T_c = 25^{\circ}C$ unless otherwise noted.

Symbol	Pa	rameter	FQF	PF12N60C / FQPF12N6	ост Unit
V _{DSS}	Drain-Source Voltage			600	V
I _D		ontinuous (T _C = 25°C) ontinuous (T _C = 100°C)		12* 7.4*	A A
I _{DM}	Drain Current - Pu	Ised (No	te 1)	48*	A
V _{GSS}	Gate-Source voltage			± 30	V
E _{AS}	Single Pulsed Avalanche Energy		e 2)	870	
I _{AR}	Avalanche Current		e 1)	12	
E _{AR}	Repetitive Avalanche Energy (Note		e 1)	22.5	mJ
dv/dt	Peak Diode Recovery dv/dt (Note 3)		e 3)	4.5	
P _D	Power Dissipation (T _C = 25°C) - Derate above 25°C			51 0.41	W W/°C
T _{J,} T _{STG}	Operating and Storage Temperature Range			-55 to +150	°C
Τ _L	Maximum Lead Temperature for Soldering Purpose, 1/8" from Case for 5 Seconds			300	°C

Thermal Characteristics

Symbol	Parameter	FQPF12N60C / FQPF12N60CT	Unit
$R_{ ext{ heta}JC}$	Thermal Resistance, Junction-to-Case, Max.	2.43	°C/W
R_{\thetaJA}	Thermal Resistance, Junction-to-Ambient, Max.	62.5	°C/W

Package Marking and Ordering Information

Part Number	Top Mark	Package	Packing Method	Reel Size	Tape Width	Quantity
FQPF12N60C	FQPF12N60C	TO-220F	Tube	N/A	N/A	50 units
FQPF12N60CT	FQPF12N60CT	TO-220F	Tube	N/A	N/A	50 units

Electrical Characteristics T_C = 25°C unless otherwise noted.

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
Off Charac	teristics					L
BV _{DSS}	Drain-Source Breakdown Voltage	$V_{GS} = 0 \text{ V}, I_{D} = 250 \ \mu\text{A}, T_{J} = 25^{\circ}\text{C}$	600			V
ΔBV _{DSS} / ΔT _J	Breakdown Voltage Temperature Coefficient	I_D = 250 µA, Referenced to 25°C		0.5		V/°C
I _{DSS}	Zero Gate Voltage Drain Current	$V_{DS} = 600 V, V_{GS} = 0 V$ $V_{DS} = 480 V, T_{C} = 125^{\circ}$			1 10	μΑ μΑ
I _{GSSF}	Gate-Body Leakage Current, Forward	V _{GS} = 30 V, V _{DS} = 0 V			100	nA
I _{GSSR}	Gate-Body Leakage Current, Reverse	V_{GS} = -30 V, V_{DS} = 0 V			-100	nA
On Charac	teristics					
V _{GS(th)}	Gate Threshold Voltage	V _{DS} = V _{GS} , I _D = 250 μA	2.0		4.0	V
R _{DS(on)}	Static Drain-Source On-Resistance	V _{GS} = 10 V, I _D = 6 A		0.53	0.65	Ω
9 _{FS}	Forward Transconductance	V _{DS} = 40 V, I _D = 6 A		13		S
Dynamic C	haracteristics	- · · ·			•	
C _{iss}	Input Capacitance	$V_{DS} = 25 V, V_{GS} = 0 V,$		1760	2290	pF
C _{oss}	Output Capacitance	f = 1.0 MHz		182	235	pF
C _{rss}	Reverse Transfer Capacitance			21	28	pF
Switching	Characteristics	- · · ·			•	
t _{d(on)}	Turn-On Delay Time	V _{DD} = 300 V, I _D = 12 A		30	70	ns
t _r	Turn-On Rise Time	$R_{G} = 25 \Omega$		85	180	ns
t _{d(off)}	Turn-Off Delay Time			140	280	ns
t _f	Turn-Off Fall Time	(Note 4)		90	190	ns
Qg	Total Gate Charge	V _{DS} = 400 V, I _D = 12 A		48	63	nC
Q _{gs}	Gate-Source Charge	V _{GS} = 10 V	-	8.5		nC
Q _{gd}	Gate-Drain Charge	(Note 4)	7	21		nC
Drain-Sour	rce Diode Characteristics and Maximur	n Ratings				
I _S	S Maximum Continuous Drain-Source Diode Forward Current				12	Α
I _{SM}	Maximum Pulsed Drain-Source Diode Forward Current				48	Α
V _{SD}	Drain-Source Diode Forward Voltage	V _{GS} = 0V, I _S = 12 A			1.4	V
t _{rr}	Reverse Recovery Time	V _{GS} = 0V, I _S = 12 A		420		ns
Q _{rr}	Reverse Recovery Charge	[−] dI _F /dt = 100 A/μs		4.9		μC

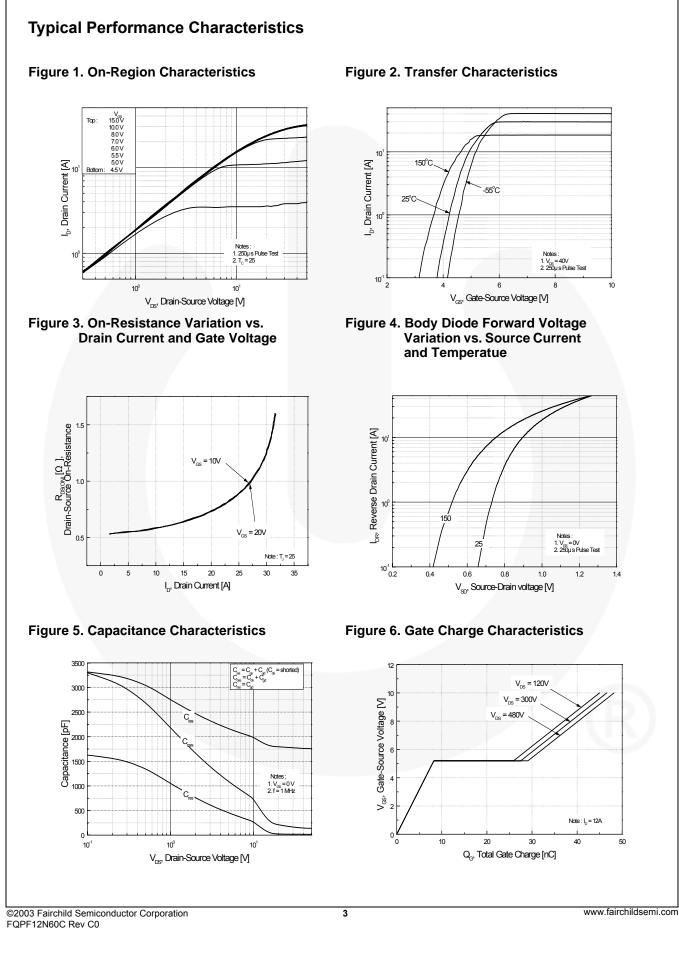
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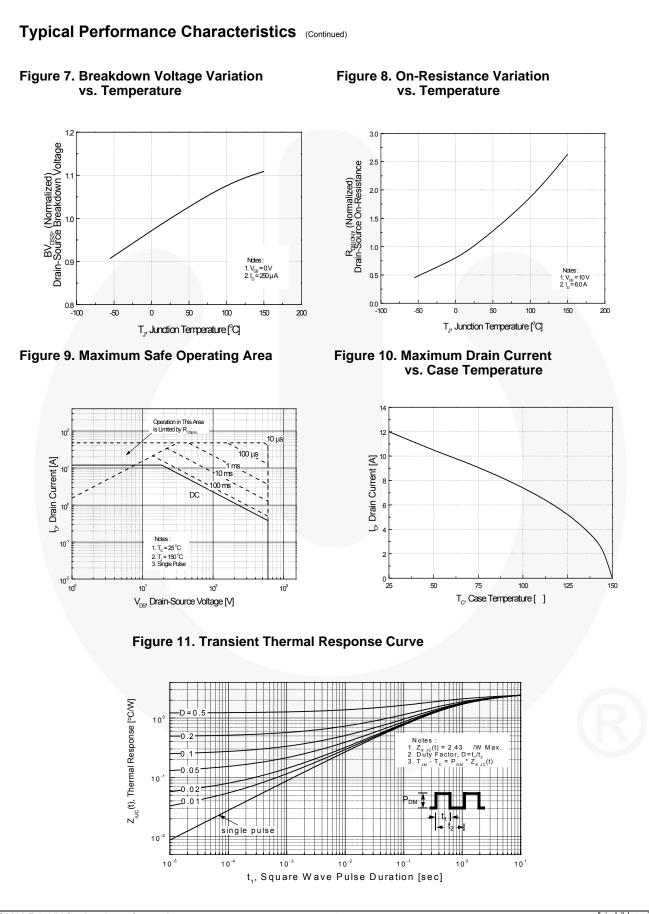
1. Repetitive rating: pulse-width limited by maximum junction temperature.

2. L = 11 mH, I_{AS} = 12 A, V_{DD} = 50 V, R_G = 25 $\Omega,$ starting T_J = 25°C.

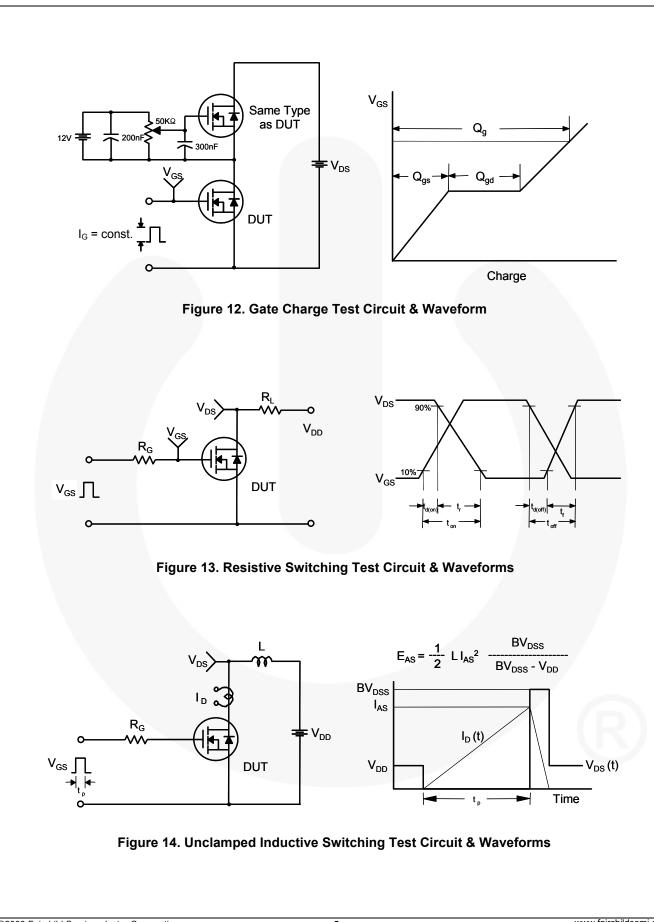
 $3.I_{SD} \leq 12$ A, di/dt ≤ 200 A/µs, $V_{DD} \leq BV_{DSS},$ starting T_J = 25°C.

4. Essentially independent of operating temperature typical characteristics.

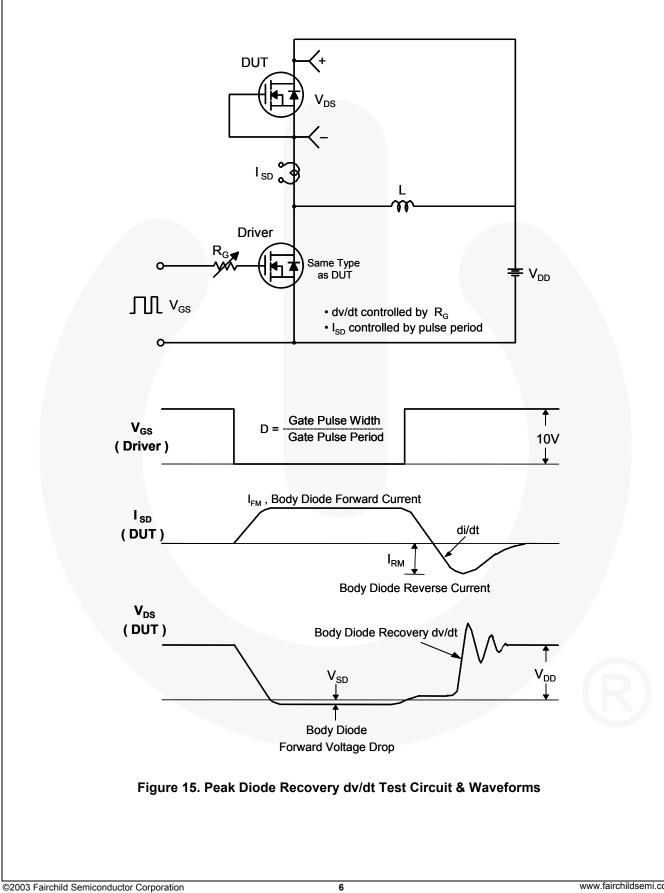


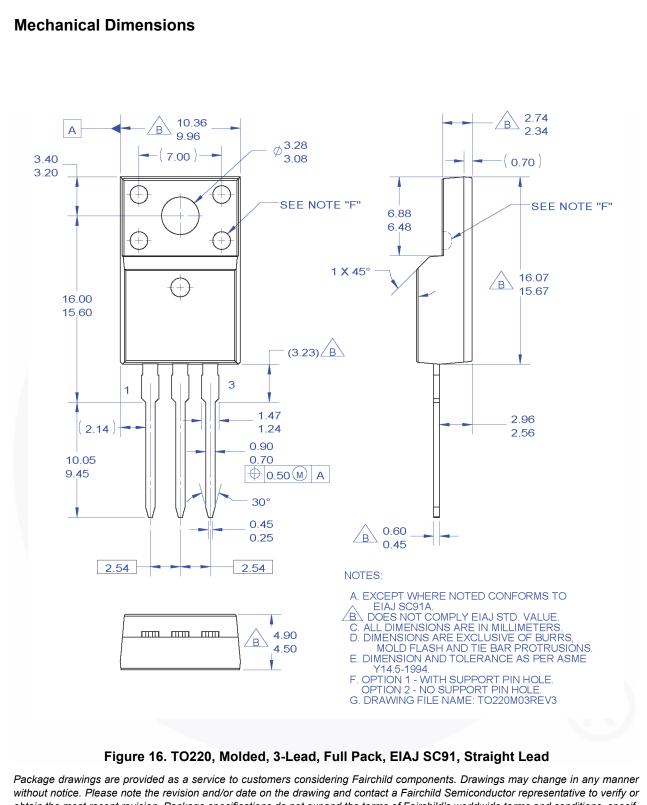


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